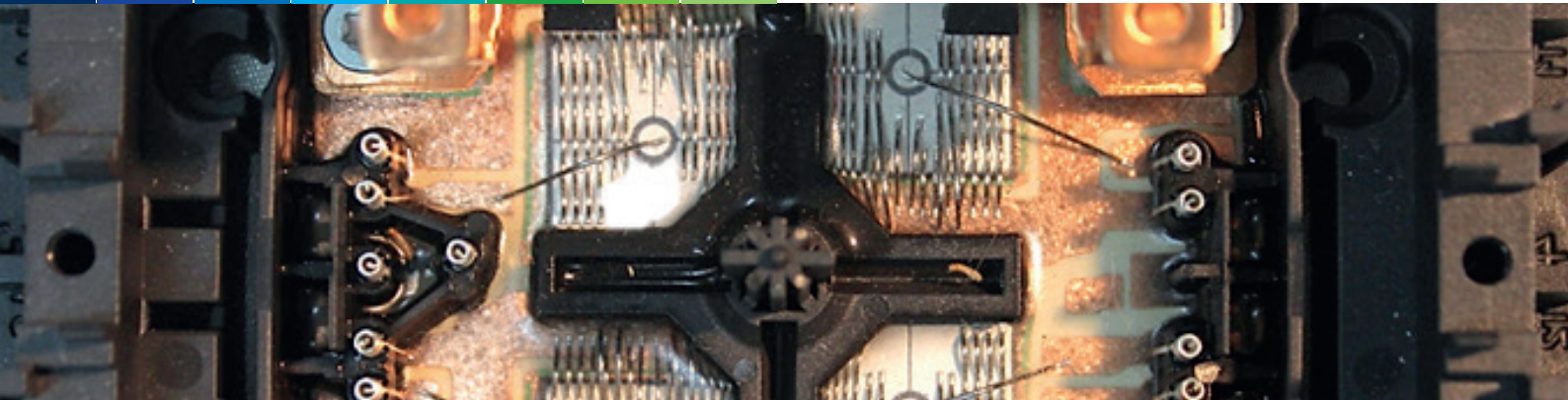


THERMAL SYSTEMS

WEBINAR

High Temperature Contact Soldering



September 17, 2020 at 9.00 a.m. and 3.00 p.m.

High Temperature Contact Soldering for Semiconductor/Power Electronics

Contact soldering with vacuum is best suited for void-free soldering of various components (e.g. IGBT) on DCB substrates. The joining of materials of mostly different materials is done under vacuum at temperatures up to 450 °C. Among other things, the negative pressure helps to minimize oxidation at the components and at the joints themselves. The heat transfer takes place both by thermal conduction and optionally by radiation.

In this webinar you will learn about the possibilities of contact soldering under vacuum and experience the ease of use of the Nexus contact soldering system live in action.

September 17, 2020 9:00 a.m. CEST (for Asia, Europe, ROW)
3:00 p.m. CEST (for Americas, Europe)

Registration:
sales@rehm-group.com

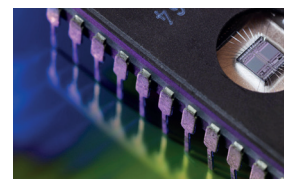
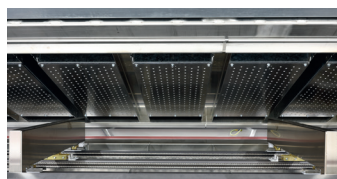
Main topics of the webinar

- Avoidance of oxidation through contact soldering
- Influence of the vacuum process during contact soldering
- LIVE DEMO

Workshop with the Nexus:

- soldering processes
- Diffusion soldering with preforms

Subject to change without notice.



TECHNOLOGY ACADEMY